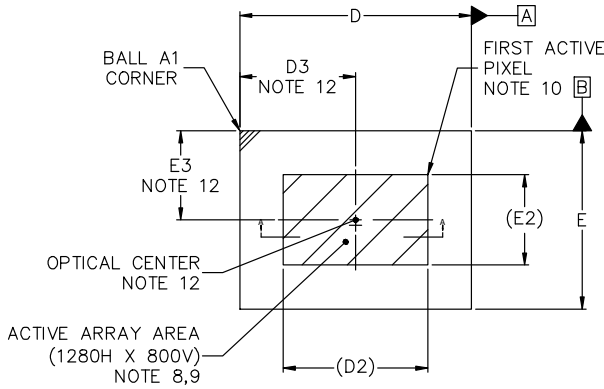


ODCSP47 5.74x4.42x0.63, 0.57P
CASE 570CZ
ISSUE B

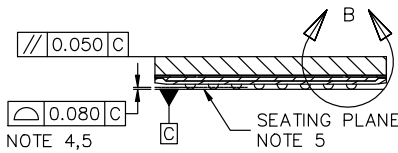
DATE 20 AUG 2024



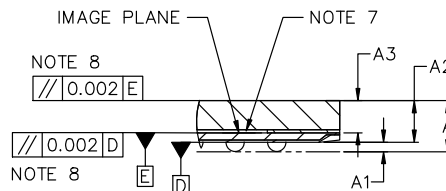
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.045 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 1^\circ$.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.001, 0.133).

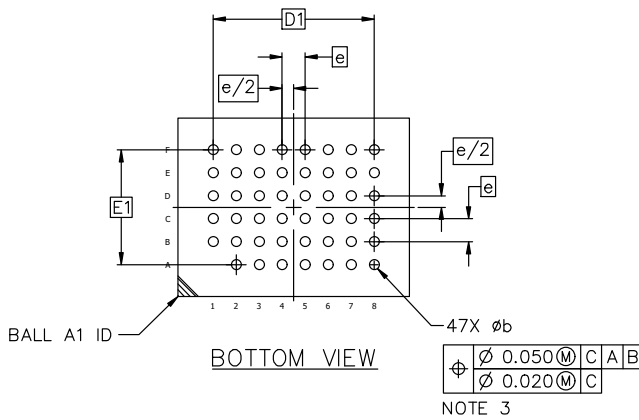


SECTION A-A



DETAIL B'
SCALE 2:1

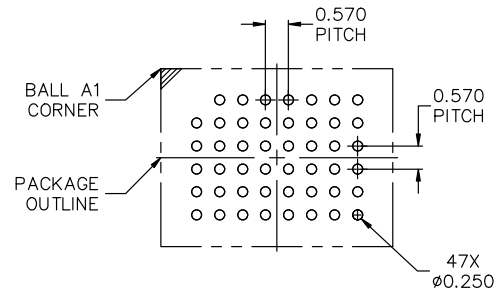
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	0.816
A1	0.100	0.130	0.160
A2	0.581	0.626	0.671
A3	0.420	0.440	0.460
b	0.220	0.250	0.280
D	5.719	5.744	5.769
D1	3.990 BSC		
D2	3.584 REF.		
D3	2.846	2.871	2.896
E	4.391	4.416	4.441
E1	2.850 BSC		
E2	2.240 REF.		
E3	2.050	2.075	2.100
e	0.570 BSC		



BOTTOM VIEW

ϕ	ϕ 0.050 (M)	C	A	B
	ϕ 0.020 (M)	C		

NOTE 3



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	ODCSP47 5.74x4.42x0.63, 0.57P	PAGE 1 OF 1

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